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(54) **COMBINATION INDUCTIVE COIL AND INTEGRATED CIRCUIT SEMICONDUCTOR CHIP IN A SINGLE LEAD FRAME PACKAGE AND METHOD THEREFOR**

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Related U.S. Application Data

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(58) **Field of Search** 438/106, 121, 438/123, 124

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(57) **ABSTRACT**

A combination inductive coil and integrated circuit semiconductor chip is provided in a single lead frame package. The lead frame is preferably made of a copper alloy and has a flat configuration. The chip is electrically connected to end portions of the inductive coil thus permitting the inductive coil to function as an antenna for the chip.

20 Claims, 2 Drawing Sheets

